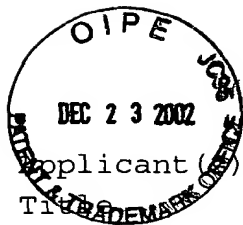


CP/2826

PATENT APPLICATION



IN THE U.S. PATENT AND TRADEMARK OFFICE

December 6, 2002

Applicant(s): Chikao IKENAGA et al.

 Title: FRAME FOR SEMICONDUCTOR PACKAGE INCLUDING PLURAL LEAD  
 FRAMES HAVING THIN PARTS OR HOLLOW ADJACENT THE  
 TERMINAL ROOTS

Serial No. : 09/850 213

Group: 2826

Confirmation No.: 9610

Filed : May 7, 2001

Examiner: Greene

Atty. Docket No.: OPS C-533

 Assistant Commissioner for Patents  
 Washington, DC 20231

Sir:

Herewith is an amendment in the above-identified application.

[ ] Statement(s) re small entity status submitted previously.

[ ] Statement(s) re small entity status enclosed.

[ ] No additional filing fee is required.

[X] The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	( ) SM Entity	Fee
Basic Fee				\$740.00	\$370.00	\$
Total Claims	(21 - 20 = 1)		x	\$ 18.00	x \$ 9.00	18.00
Indep. Claims	(5 - 4 = 1)		x	\$ 84.00	x \$ 42.00	84.00
[ ] Multiple Dep. Claim			+	\$280.00	+	\$140.00
* * * TOTAL FILING FEE * * *						\$ 102.00

[X] A Check for \$102.00 is enclosed to cover fees.

 [X] Please credit any overpayment, or charge any additional filing  
 fee or application processing fee required under 37 CFR 1.16 or  
 1.17 by this communication, to Deposit Account No. 06-1382. A  
 duplicate copy of this sheet is enclosed.

IN DUPLICATE

Respectfully submitted,

LLC/cc

Encl: Listed above

Liane L. Churney Reg. No. 40 694

## CERTIFICATE OF MAILING

 I hereby certify that this correspondence is being deposited  
 with the United States Postal Service as first class mail in an  
 envelope addressed to: Assistant Commissioner for Patents,  
 Washington, DC 20231, on December 6, 2002.

Respectfully submitted,

130.0112

Liane L. Churney

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IN THE U.S. PATENT AND TRADEMARK OFFICE

December 6, 2002

PATENT APPLICATION

RECEIVED

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TECHNOLOGY CENTER 2800

#10/C  
1-2-03  
Payton

Applicant(s): Chikao IKENAGA et al.

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International Application No.: N/A

International Filing Date: N/A

Atty. Docket No.: OPS C-533

Assistant Commissioner for Patents  
Washington, DC 20231

AMENDMENT AND RESPONSE TO RESTRICTION REQUIREMENT

Sir:

In response to the Office Action dated November 6, 2002,  
Applicants amend as follows:

IN THE CLAIMS

Please amend Claim 4 as follows. A marked-up version of  
the amended claim is enclosed herewith, showing the changes  
made by the current amendment.

4. (Amended) A frame for forming individual  
semiconductor packages, said frame comprising a plurality of  
lead frames arranged in a matrix and semiconductor devices  
respectively mounted on die pads supported on the individual  
lead frames by suspending leads, each said lead frame having a  
metal lead which defines a boundary between said lead frame  
and an adjacent lead frame, and pairs of terminals project in  
opposite directions from each said lead disposed between an  
adjacent pair of lead frames, wherein roots of the respective

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01 FC:1201  
02 FC:1202

84.00 OP  
18.00 OP